

广东星坤科技股份有限公司

DATE	日期
DESCRIPTION	文件工程章

MARK	DESCRIPTION	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES
	REVISIONS				
					ANGLAR ±5°
					L ≤ 4 ±0.2
					4 < L ≤ 16 ±0.3
					16 < L ≤ 63 ±0.4
					L > 63 ±0.5



DSND	SCALE: N/A	MODEL TYPE:
DWN	VIEW:	PART NO.: X1304WVS-52A-LPV10
CHKD	UNIT: mm/in	DWG NO.: X-X1304WVS-52A-LPV10
APPD	SIZE: A4	WEIGHT
		SHEET 1/1
		REVISION A0

XKB INDUSTRIAL PRECISION CO., LIMITED

NOTES 注释:

1. MATERIAL 材料:

HOUSING外壳: THERMOPLASTIC, HIGH TEMP.,  
UL94V-0;BLACK COLOR

CONTACTS触点: COPPER ALLOY.

PEGS螺钉: COPPER ALLOY.

2. FINISH 饰面:

CONTACT触点:SELECTEIVE GOLD PLATING ON CONTACT AREA.  
100μ"MIN. MATTE TIN PLATING ON SOLDER TAILS,  
50μ" MIN. NICKEL UNDERPLATING OVERALL.

PEGS螺钉: 120u" MIN. MATTE-TIN OVER 50u" MIN. NICKEL.

X1304 W V S - 52 A - LP V10

- ① ② ③④ ⑤ ⑥ ⑦ ⑧

①Series Number

②Terminal form: W-Wafer

③Welding Board Angle : V-Stright Angle 180°

④Welding Way:S-SMT

⑤No.of Pins: 52 PIN

⑥HEIGHT: A 4.0mm;B 5.2mm;C 5.6mm;D 6.8mm;  
E 7.0mm;F 8.0mm;G 9.0mm;H 9.9mm

⑦Plastic material: LP-PCP UL94V-0

⑧Contact Plating:V01-Gold Flash 1"u";  
V10-Gold Flash 10"u";  
V30-Gold Flash 30"u"

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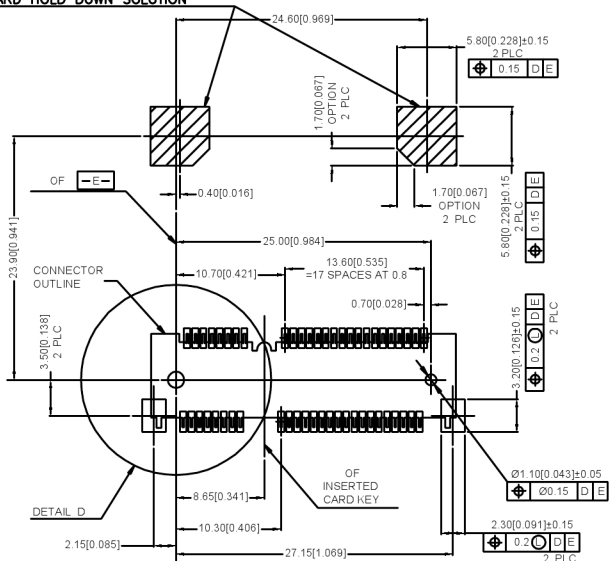
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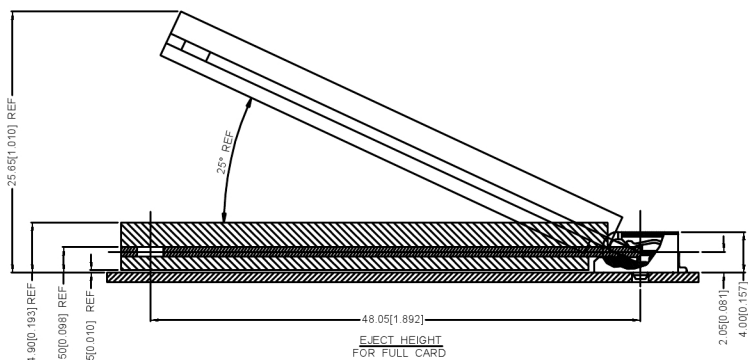


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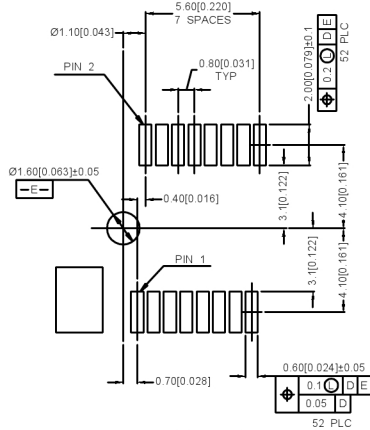
COMPONENT KEEP OUT AREA FOR  
CARD HOLD DOWN SOLUTION



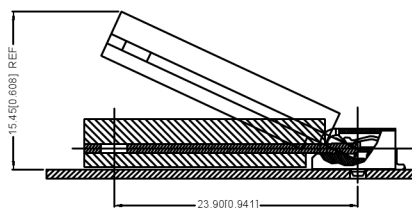
—D— IS THE TOP SURFACE OF PCB.  
RECOMMENDED P.C. BOARD PATTERN LAYOUT  
FOR HALF CARD CONNECTOR  
(TOP VIEW)



EJECT HEIGHT  
FOR FULL CARD

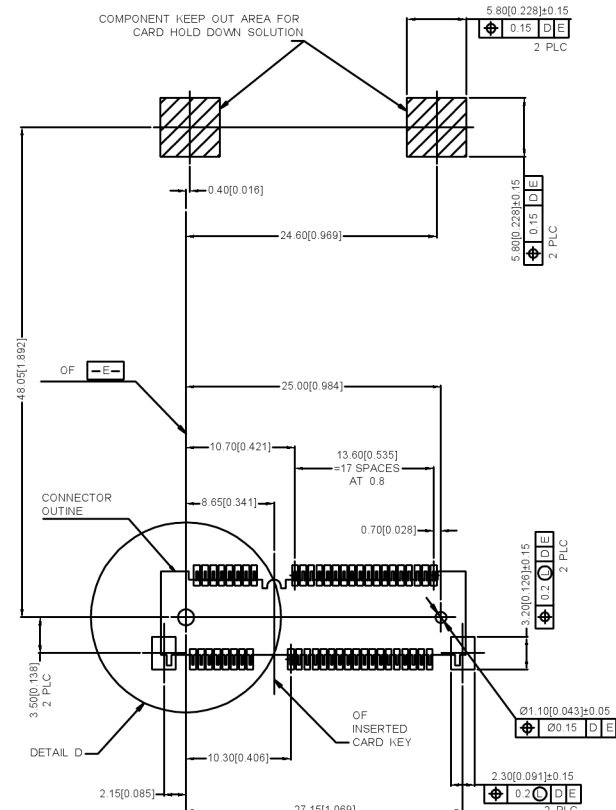


DETAIL D  
SCALE 2:1



EJECT HEIGHT  
FOR HALF CARD

COMPONENT KEEP OUT AREA FOR  
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REVISIONS  
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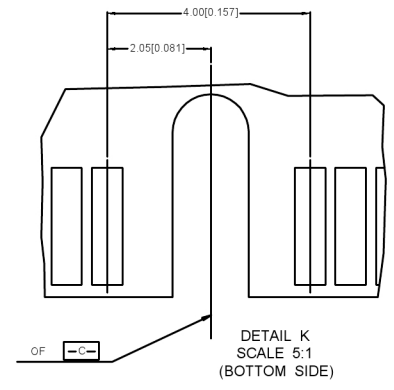
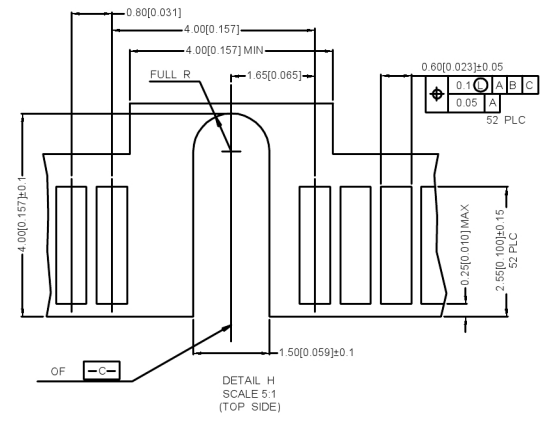
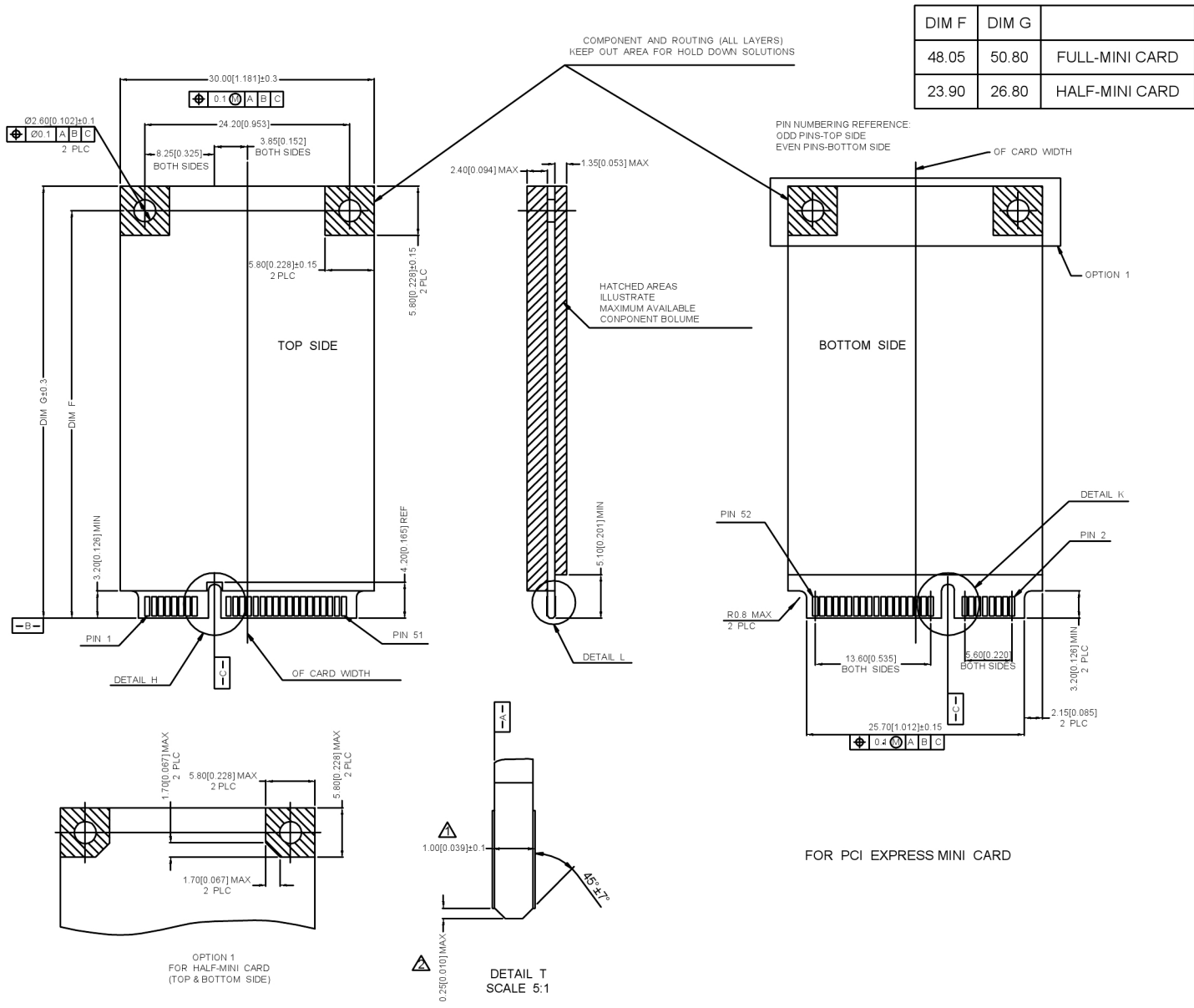
UNSPECIFIED TOLERANCES

XKLB

XKB INDUSTRIAL PRECISION CO., LIMITED

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DWN	VIEW:	PART NO.:
CHKD	UNIT: mm/in	X1304WWS-52A-LPV10
APPD	SIZE: A4	DWG NO.:
		X-X1304WWS-52A-LPV10

WEIGHT	SHEET	REVISION
	1/1	A0



NOTES 注释:

- △ CARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR METALLIZATION.  
卡片厚度适用于所有接线片，包括电镀和/或金属化。
- △ EDGE BEVEL MUST BE IPRESENT AND FREE OF CUTTING CONTACT MATERIALS BURRS FROM AND PCB  
边缘斜面必须均匀且无切割接触材料毛刺和PCB

FOR PCI EXPRESS MINI CARD

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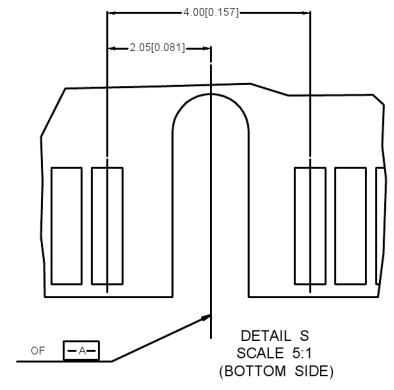
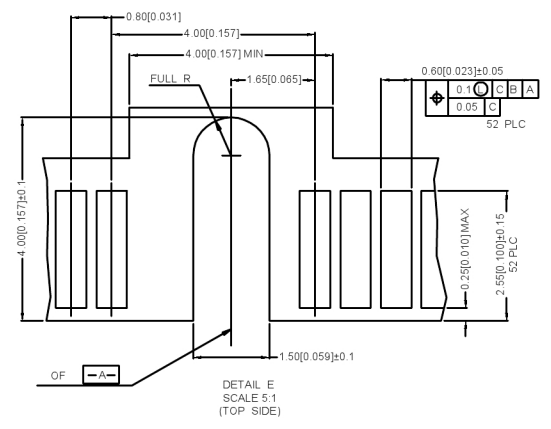
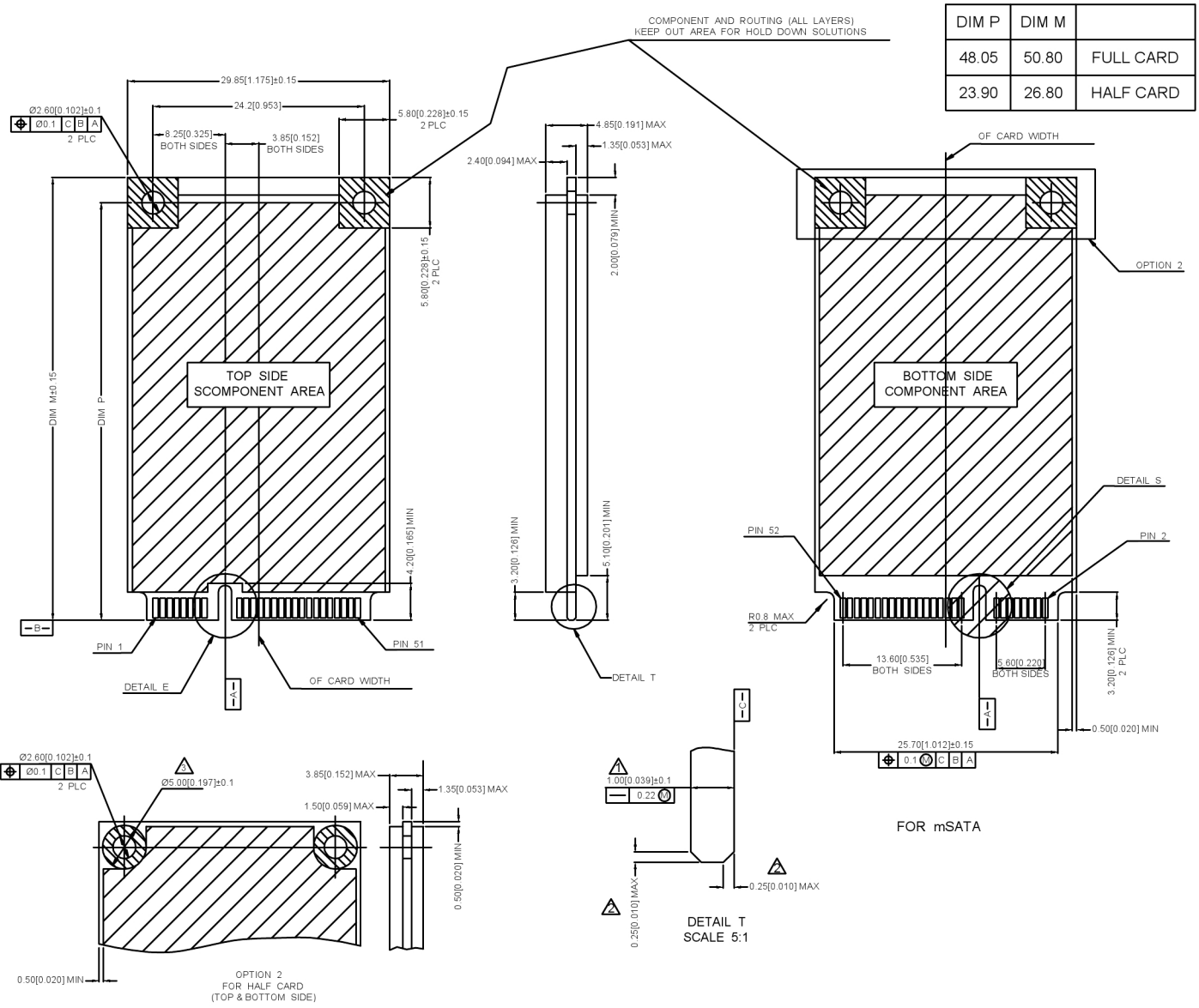
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边缘斜面必须均匀且无切割接触材料毛刺和PCB
- △ COMPONENT AND ROUTING (TOP/BOTTOM LAYER) KEEP OUT AREA FOR HOLD DOWN SOLUTIONS.  
元件和布线(顶层/底层)为压紧解决方案留出区域

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